

Quadruple Operational Amplifiers

FEATURES

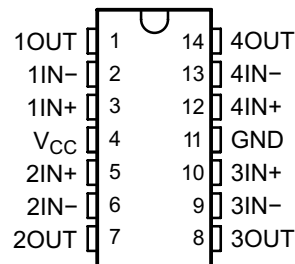
- **2-kV ESD Protection for:**
 - LM224K, LM224KA
 - LM324K, LM324KA
 - LM2902K, LM2902KV, LM2902KAV
- **Wide Supply Ranges**
 - **Single Supply: 3 V to 32 V (26 V for LM2902)**
 - **Dual Supplies: ± 1.5 V to ± 16 V (± 13 V for LM2902)**
- **Low Supply-Current Drain Independent of Supply Voltage: 0.8 mA Typ**
- **Common-Mode Input Voltage Range Includes Ground, Allowing Direct Sensing Near Ground**
- **Low Input Bias and Offset Parameters**
 - **Input Offset Voltage: 3 mV Typ**
A Versions: 2 mV Typ
 - **Input Offset Current: 2 nA Typ**
 - **Input Bias Current: 20 nA Typ**
A Versions: 15 nA Typ
- **Differential Input Voltage Range Equal to Maximum-Rated Supply Voltage: 32 V (26 V for LM2902)**
- **Open-Loop Differential Voltage Amplification: 100 V/mV Typ**
- **Internal Frequency Compensation**
- **On Products Compliant to MIL-PRF-38535, All Parameters Are Tested Unless Otherwise Noted. On All Other Products, Production Processing Does Not Necessarily Include Testing of All Parameters.**

DESCRIPTION

These devices consist of four independent high-gain frequency-compensated operational amplifiers that are designed specifically to operate from a single supply over a wide range of voltages. Operation from split supplies also is possible if the difference between the two supplies is 3 V to 32 V (3 V to 26 V for the LM2902 device), and V_{CC} is at least 1.5 V more positive than the input common-mode voltage. The low supply-current drain is independent of the magnitude of the supply voltage.

Applications include transducer amplifiers, dc amplification blocks, and all the conventional operational-amplifier circuits that now can be more easily implemented in single-supply-voltage systems. For example, the LM124 device can be operated directly from the standard 5-V supply that is used in digital systems and provides the required interface electronics, without requiring additional ± 15 -V supplies.

LM124 . . . D, J, OR W PACKAGE
 LM124A . . . J OR W PACKAGE
 LM224, LM224A, LM224K, LM224KA . . . D OR N PACKAGE
 LM324, LM324K . . . D, N, NS, OR PW PACKAGE
 LM324A . . . D, DB, N, NS, OR PW PACKAGE
 LM324KA . . . D, N, NS, OR PW PACKAGE
 LM2902 . . . D, N, NS, OR PW PACKAGE
 LM2902K . . . D, DB, N, NS, OR PW PACKAGE
 LM2902KV, LM2902KAV . . . D OR PW PACKAGE
 (TOP VIEW)

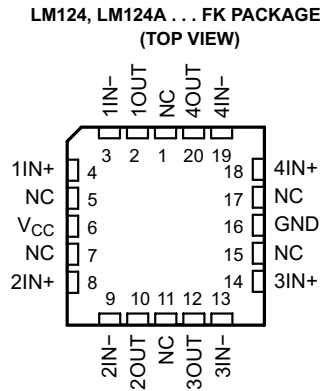


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



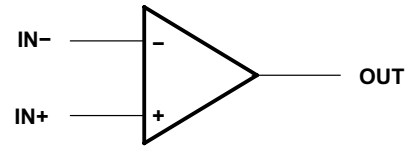
This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

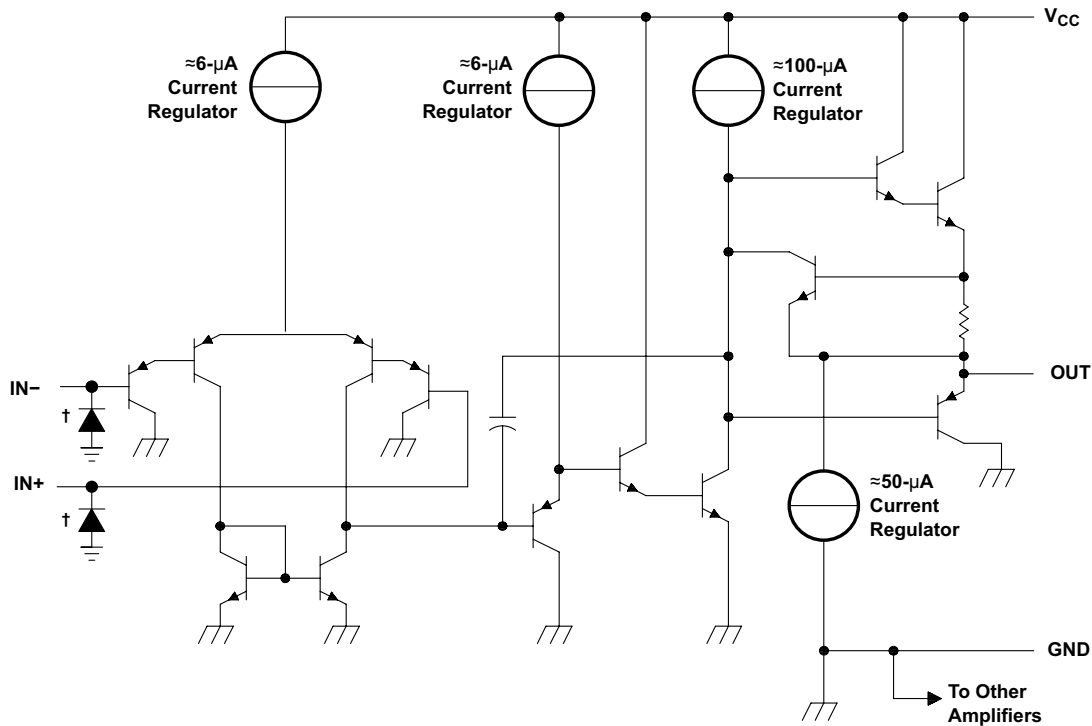


NC – No internal connection

Symbol (Each Amplifier)



Schematic (Each Amplifier)



COMPONENT COUNT (total device)	
Epi-FET	1
Transistors	95
Diodes	4
Resistors	11
Capacitors	4

† ESD protection cells - available on LM324K and LM324KA only

Absolute Maximum Ratings

 over operating free-air temperature range (unless otherwise noted)⁽¹⁾

	LM2902	ALL OTHER DEVICES	UNIT
Supply voltage, V_{CC} ⁽²⁾	±13 or 26	±16 or 32	V
Differential input voltage, V_{ID} ⁽³⁾	±26	±32	V
Input voltage, V_I (either input)	–0.3 to 26	–0.3 to 32	V
Duration of output short circuit (one amplifier) to ground at (or below) $T_A = 25^\circ\text{C}$, $V_{CC} \leq 15\text{ V}$ ⁽⁴⁾	Unlimited	Unlimited	
Package thermal impedance, θ_{JA} ⁽⁴⁾⁽⁵⁾	D package	86	°C/W
	DB package	96	
	N package	80	
	NS package	76	
	PW package	113	
Package thermal impedance, θ_{JC} ⁽⁶⁾⁽⁷⁾	FK package		°C/W
	J package	5.61	
	W package	15.05	
Operating virtual junction temperature, T_J	150	150	°C
Case temperature for 60 seconds	FK package	260	°C
Lead temperature 1.6 mm (1/16 inch) from case for 60 seconds	J or W package	300	°C
Storage temperature range, T_{stg}	–65 to 150	–65 to 150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values (except differential voltages and V_{CC} specified for the measurement of I_{OS}) are with respect to the network GND.
- (3) Differential voltages are at $IN+$, with respect to $IN-$.
- (4) Short circuits from outputs to V_{CC} can cause excessive heating and eventual destruction.
- (5) Maximum power dissipation is a function of $T_{J(max)}$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_{J(max)} - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
- (6) Maximum power dissipation is a function of $T_{J(max)}$, θ_{JA} , and T_C . The maximum allowable power dissipation at any allowable case temperature is $P_D = (T_{J(max)} - T_C)/\theta_{JC}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
- (7) The package thermal impedance is calculated in accordance with MIL-STD-883

ESD Protection

TEST CONDITIONS		TYP	UNIT
Human-Body Model	LM224K, LM224KA, LM324K, LM324KA, LM2902K, LM2902KV, LM2902KAV	±2	kV

Electrical Characteristics

at specified free-air temperature, $V_{CC} = 5\text{ V}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS ⁽¹⁾	T_A ⁽²⁾	LM124, LM224			LM324, LM324K			UNIT		
			MIN	TYP ⁽³⁾	MAX	MIN	TYP ⁽³⁾	MAX			
V_{IO} Input offset voltage	$V_{CC} = 5\text{ V}$ to MAX, $V_{IC} = V_{ICRmin}$, $V_O = 1.4\text{ V}$	25°C		3	5		3	7	mV		
		Full range			7			9			
I_{IO} Input offset current	$V_O = 1.4\text{ V}$	25°C		2	30		2	50	nA		
		Full range			100			150			
I_{IB} Input bias current	$V_O = 1.4\text{ V}$	25°C		-20	-150		-20	-250	nA		
		Full range			-300			-500			
V_{ICR} Common-mode input voltage range	$V_{CC} = 5\text{ V}$ to MAX	25°C		0 to $V_{CC} - 1.5$			0 to $V_{CC} - 1.5$		V		
		Full range		0 to $V_{CC} - 2$			0 to $V_{CC} - 2$				
V_{OH} High-level output voltage	$R_L = 2\text{ k}\Omega$	25°C		$V_{CC} - 1.5$			$V_{CC} - 1.5$			V	
		25°C		$V_{CC} - 1.5$			$V_{CC} - 1.5$				
	$V_{CC} = \text{MAX}$	$R_L = 2\text{ k}\Omega$	Full range		26			26			
		$R_L \geq 10\text{ k}\Omega$	Full range		27	28		27	28		
V_{OL} Low-level output voltage	$R_L \leq 10\text{ k}\Omega$	Full range		5	20		5	20	mV		
A_{VD} Large-signal differential voltage amplification	$V_{CC} = 15\text{ V}$, $V_O = 1\text{ V}$ to 11 V, $R_L \geq 2\text{ k}\Omega$	25°C		50	100		25	100	V/mV		
		Full range		25			15				
CMRR Common-mode rejection ratio	$V_{IC} = V_{ICRmin}$	25°C		70	80		65	80	dB		
k_{SVR} Supply-voltage rejection ratio ($\Delta V_{CC} / \Delta V_{IO}$)		25°C		65	100		65	100	dB		
V_{O1} / V_{O2} Crosstalk attenuation	$f = 1\text{ kHz}$ to 20 kHz	25°C		120			120			dB	
I_O Output current	$V_{CC} = 15\text{ V}$, $V_{ID} = 1\text{ V}$, $V_O = 0$	Source	25°C		-20	-30	-60	-20	-30	-60	mA
			Full range		-10			-10			
	$V_{CC} = 15\text{ V}$, $V_{ID} = -1\text{ V}$, $V_O = 15\text{ V}$	Sink	25°C		10	20		10	20		
			Full range		5			5			
	$V_{ID} = -1\text{ V}$, $V_O = 200\text{ mV}$	25°C		12	30		12	30	μA		
I_{OS} Short-circuit output current	V_{CC} at 5 V, $V_O = 0$, GND at -5 V	25°C		± 40	± 60		± 40	± 60	mA		
I_{CC} Supply current (four amplifiers)	$V_O = 2.5\text{ V}$, No load	Full range		0.7	1.2		0.7	1.2	mA		
	$V_{CC} = \text{MAX}$, $V_O = 0.5 V_{CC}$, No load	Full range		1.4	3		1.4	3			

- (1) All characteristics are measured under open-loop conditions, with zero common-mode input voltage, unless otherwise specified. MAX V_{CC} for testing purposes is 26 V for LM2902 and 30 V for the others.
- (2) Full range is -55°C to 125°C for LM124, -25°C to 85°C for LM224, and 0°C to 70°C for LM324.
- (3) All typical values are at $T_A = 25^\circ\text{C}$

Electrical Characteristics

 at specified free-air temperature, $V_{CC} = 5\text{ V}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS ⁽¹⁾		T_A ⁽²⁾	LM2902			LM2902V			UNIT		
				MIN	TYP ⁽³⁾	MAX	MIN	TYP ⁽³⁾	MAX			
V_{IO} Input offset voltage	$V_{CC} = 5\text{ V to MAX,}$ $V_{IC} = V_{ICRmin},$ $V_O = 1.4\text{ V}$	Non-A-suffix devices	25°C	3		7	3		7	mV		
			Full range	10			10					
		A-suffix devices	25°C				1		2			
			Full range				4					
$\Delta V_{IO}/\Delta T$ Input offset voltage temperature drift	$R_S = 0\ \Omega$		Full range				7		$\mu\text{V}/^\circ\text{C}$			
I_{IO} Input offset current	$V_O = 1.4\text{ V}$		25°C	2		50	2		50	nA		
			Full range	300			150					
$\Delta I_{IO}/\Delta T$ Input offset voltage temperature drift			Full range				10		$\text{pA}/^\circ\text{C}$			
I_{IB} Input bias current	$V_O = 1.4\text{ V}$		25°C	–20		–250	–20		–250	nA		
			Full range	–500			–500					
V_{ICR} Common-mode input voltage range	$V_{CC} = 5\text{ V to MAX}$		25°C	0 to $V_{CC} - 1.5$			0 to $V_{CC} - 1.5$		V			
			Full range	0 to $V_{CC} - 2$			0 to $V_{CC} - 2$					
V_{OH} High-level output voltage	$R_L = 2\text{ k}\Omega$ $R_L = 10\text{ k}\Omega$ $V_{CC} = \text{MAX}$		25°C							V		
			25°C	$V_{CC} - 1.5$		$V_{CC} - 1.5$						
		Full range	$R_L = 2\text{ k}\Omega$	22		26						
			$R_L \geq 10\text{ k}\Omega$	23		24		27				
V_{OL} Low-level output voltage	$R_L \leq 10\text{ k}\Omega$		Full range	5		20	5		20	mV		
A_{VD} Large-signal differential voltage amplification	$V_{CC} = 15\text{ V,}$ $V_O = 1\text{ V to }11\text{ V,}$ $R_L \geq 2\text{ k}\Omega$		25°C	25		100	25		100	V/mV		
			Full range	15			15					
CMRR Common-mode rejection ratio	$V_{IC} = V_{ICRmin}$		25°C	50		80	60		80	dB		
k_{SVR} Supply-voltage rejection ratio ($\Delta V_{CC}/\Delta V_{IO}$)			25°C	50		100	60		100	dB		
V_{O1}/V_{O2} Crosstalk attenuation	$f = 1\text{ kHz to }20\text{ kHz}$		25°C	120			120			dB		
I_O Output current	$V_{CC} = 15\text{ V,}$ $V_{ID} = 1\text{ V,}$ $V_O = 0$	Source	25°C	–20		–30	–60	–20		–30	–60	mA
			Full range	–10			–10					
	Sink	25°C	10		20	10		20				
		Full range	5			5						
	$V_{ID} = -1\text{ V, }V_O = 200\text{ mV}$		25°C	30			12		40	μA		
I_{OS} Short-circuit output current	V_{CC} at 5 V, $V_O = 0$, GND at –5 V		25°C	± 40		± 60	± 40		± 60	mA		
I_{CC} Supply current (four amplifiers)	$V_O = 2.5\text{ V, No load}$		Full range	0.7		1.2	0.7		1.2	mA		
	$V_{CC} = \text{MAX, }V_O = 0.5\text{ }V_{CC},$ No load		Full range	1.4		3	1.4		3			

- All characteristics are measured under open-loop conditions, with zero common-mode input voltage, unless otherwise specified. MAX V_{CC} for testing purposes is 26 V for LM2902 and 32 V for LM2902V.
- Full range is -40°C to 125°C for LM2902.
- All typical values are at $T_A = 25^\circ\text{C}$.

Electrical Characteristics

at specified free-air temperature, $V_{CC} = 5\text{ V}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS ⁽¹⁾		T_A ⁽²⁾	LM124A			LM224A			LM324A, LM324KA			UNIT
				MIN	TYP ⁽³⁾	MAX	MIN	TYP ⁽³⁾	MAX	MIN	TYP ⁽³⁾	MAX	
V_{IO} Input offset voltage	$V_{CC} = 5\text{ V to } 30\text{ V},$ $V_{IC} = V_{ICRmin},$ $V_O = 1.4\text{ V}$		25°C			2		2	3		2	3	mV
			Full range			4		4		5			
I_{IO} Input offset current	$V_O = 1.4\text{ V}$		25°C				2	15		2	30	nA	
			Full range			30		30		75			
I_{IB} Input bias current	$V_O = 1.4\text{ V}$		25°C			-50	-15	-80		-15	-100	nA	
			Full range			-100		-100		-200			
V_{ICR} Common-mode input voltage range	$V_{CC} = 30\text{ V}$		25°C	0 to $V_{CC} - 1.5$			0 to $V_{CC} - 1.5$			0 to $V_{CC} - 1.5$			V
			Full range	0 to $V_{CC} - 2$			0 to $V_{CC} - 2$			0 to $V_{CC} - 2$			
V_{OH} High-level output voltage	$R_L = 2\text{ k}\Omega$ $V_{CC} = 30\text{ V}$	$R_L = 2\text{ k}\Omega$ $R_L \geq 10\text{ k}\Omega$	25°C	$V_{CC} - 1.5$			$V_{CC} - 1.5$			$V_{CC} - 1.5$			V
			Full range	26			26			26			
V_{OL} Low-level output voltage	$R_L \leq 10\text{ k}\Omega$		25°C	20			5			20			mV
			Full range	20			5			20			
A_{VD} Large-signal differential voltage amplification	$V_{CC} = 15\text{ V},$ $V_O = 1\text{ V to } 11\text{ V},$ $R_L \geq 2\text{ k}\Omega$		25°C	50	100		50	100		25	100	V/mV	
			Full range	25			25			15			
CMRR Common-mode rejection ratio	$V_{IC} = V_{ICRmin}$		25°C	70			70	80		65	80	dB	
k_{SVR} Supply-voltage rejection ratio ($\Delta V_{CC} / \Delta V_{IO}$)			25°C	65			65	100		65	100	dB	
V_{O1} / V_{O2} Crosstalk attenuation	$f = 1\text{ kHz to } 20\text{ kHz}$		25°C	120			120			120			dB
I_O Output current	$V_{CC} = 15\text{ V},$ $V_{ID} = 1\text{ V},$ $V_O = 0$	Source	25°C	-20			-20 -30 -60			-20 -30 -60			mA
			Full range	-10			-10			-10			
	$V_{CC} = 15\text{ V},$ $V_{ID} = -1\text{ V},$ $V_O = 15\text{ V}$	Sink	25°C	10			10 20			1 20			
			Full range	5			5			5			
$V_{ID} = -1\text{ V}, V_O = 200\text{ mV}$			25°C	12			12 30			12 30			μA
I_{OS} Short-circuit output current	V_{CC} at 5 V, GND at -5 V, $V_O = 0$		25°C	± 40 ± 60			± 40 ± 60			± 40 ± 60			mA
I_{CC} Supply current (four amplifiers)	$V_O = 2.5\text{ V},$ No load		Full range	0.7 1.2			0.7 1.2			0.7 1.2			mA
	$V_{CC} = 30\text{ V}, V_O = 15\text{ V},$ No load		Full range	1.4 3.			1.4 3.			1.4 3.			

- (1) All characteristics are measured under open-loop conditions, with zero common-mode input voltage, unless otherwise specified.
- (2) Full range is -55°C to 125°C for LM124A, -25°C to 85°C for LM224A, and 0°C to 70°C for LM324A.
- (3) All typical values are at $T_A = 25^\circ\text{C}$.

Operating Conditions

 $V_{CC} = \pm 15\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	TYP	UNIT
SR	Slew rate at unity gain	$R_L = 1\text{ M}\Omega$, $C_L = 30\text{ pF}$, $V_I = \pm 10\text{ V}$ (see Figure 1)	0.5	V/ μs
B_1	Unity-gain bandwidth	$R_L = 1\text{ M}\Omega$, $C_L = 20\text{ pF}$ (see Figure 1)	1.2	MHz
V_n	Equivalent input noise voltage	$R_S = 100\ \Omega$, $V_I = 0\text{ V}$, $f = 1\text{ kHz}$ (see Figure 2)	35	nV/ $\sqrt{\text{Hz}}$

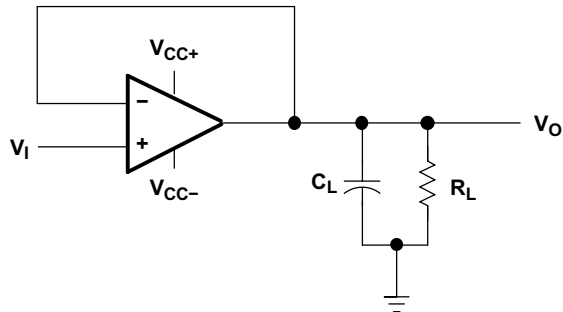


Figure 1. Unity-Gain Amplifier

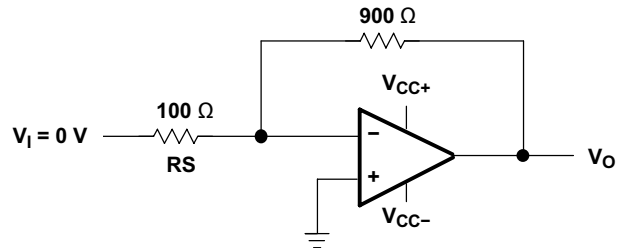


Figure 2. Noise-Test Circuit

REVISION HISTORY

Changes from Revision U (August 2010) to Revision V	Page
• Updated document to new TI data sheet format - no specification changes.	1
• Updated Features.	1
• Added ESD warning.	2
• Removed Ordering Information table.	2

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)
5962-7704301VCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-7704301VC A LM124JQMLV
5962-9950403V9B	ACTIVE	XCEPT	KGD	0	100	TBD	Call TI	N / A for Pkg Type	-55 to 125	
5962-9950403VCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9950403VC A LM124AJQMLV
77043012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	77043012A LM124FKB
7704301CA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	7704301CA LM124JB
7704301DA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	7704301DA LM124WB
77043022A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	77043022A LM124AFKB
7704302CA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	7704302CA LM124AJB
7704302DA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	7704302DA LM124AWB
JM38510/11005BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510 /11005BCA
LM124ADR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	-55 to 125	
LM124AFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	77043022A LM124AFKB
LM124AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	LM124AJ
LM124AJB	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	7704302CA LM124AJB
LM124AWB	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	7704302DA LM124AWB
LM124D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM124
LM124DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM124

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)
LM124DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM124
LM124DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM124
LM124FKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	77043012A LM124FKB
LM124J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	LM124J
LM124JB	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	7704301CA LM124JB
LM124N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	-55 to 125	
LM124W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	LM124W
LM124WB	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	7704301DA LM124WB
LM224AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM224A
LM224ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM224A
LM224ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	-25 to 85	LM224A
LM224ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM224A
LM224ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM224A
LM224AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-25 to 85	LM224AN
LM224ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-25 to 85	LM224AN
LM224D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM224
LM224DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM224
LM224DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	-25 to 85	LM224
LM224DRG3	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-25 to 85	LM224

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)
LM224DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM224
LM224KAD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM224KA
LM224KADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM224KA
LM224KADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM224KA
LM224KADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM224KA
LM224KAN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-25 to 85	LM224KAN
LM224KANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-25 to 85	LM224KAN
LM224KDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM224K
LM224KDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM224K
LM224KN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-25 to 85	LM224KN
LM224KNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-25 to 85	LM224KN
LM224N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-25 to 85	LM224N
LM224NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-25 to 85	LM224N
LM2902D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2902
LM2902DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2902
LM2902DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	-40 to 125	LM2902
LM2902DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2902
LM2902DRG3	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	LM2902

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)
LM2902DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2902
LM2902KAVQDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902KA
LM2902KAVQDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902KA
LM2902KAVQPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902KA
LM2902KAVQPWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902KA
LM2902KD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2902K
LM2902KDB	ACTIVE	SSOP	DB	14	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902K
LM2902KDBE4	ACTIVE	SSOP	DB	14	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902K
LM2902KDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2902K
LM2902KDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2902K
LM2902KN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	LM2902KN
LM2902KNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	LM2902KN
LM2902KNSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2902K
LM2902KNSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2902K
LM2902KPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902K
LM2902KPWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902K
LM2902KPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902K
LM2902KPWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902K

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)
LM2902KVQDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902KV
LM2902KVQDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902KV
LM2902KVQPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902KV
LM2902KVQPWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902KV
LM2902N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU CU SN	N / A for Pkg Type	-40 to 125	LM2902N
LM2902NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	LM2902N
LM2902NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2902
LM2902PW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902
LM2902PWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI	-40 to 125	
LM2902PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	-40 to 125	L2902
LM2902PWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902
LM2902PWRG3	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	L2902
LM2902PWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902
LM2902QN	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	-40 to 125	
LM324AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324A
LM324ADBLE	OBSOLETE	SSOP	DB	14		TBD	Call TI	Call TI		
LM324ADBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324A
LM324ADBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324A
LM324ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324A

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)
LM324ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	0 to 70	LM324A
LM324ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324A
LM324ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324A
LM324AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	LM324AN
LM324ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	LM324AN
LM324ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324A
LM324ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324A
LM324APW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L324A
LM324APWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L324A
LM324APWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L324A
LM324APWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI		
LM324APWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	0 to 70	L324A
LM324APWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L324A
LM324APWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L324A
LM324D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324
LM324DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324
LM324DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324
LM324DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	0 to 70	LM324

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)
LM324DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324
LM324DRG3	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	LM324
LM324DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324
LM324KAD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324KA
LM324KADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324KA
LM324KADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324KA
LM324KAN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	LM324KAN
LM324KANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324KA
LM324KAPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L324KA
LM324KAPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L324KA
LM324KAPWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L324KA
LM324KD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324K
LM324KDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324K
LM324KN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	LM324KN
LM324KNSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324K
LM324KPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L324K
LM324KPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L324K
LM324KPWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L324K

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)
LM324N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU CU SN	N / A for Pkg Type	0 to 70	LM324N
LM324NE3	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 70	LM324N
LM324NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	LM324N
LM324NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324
LM324NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324
LM324NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324
LM324PW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L324
LM324PWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L324
LM324PWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L324
LM324PWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI	0 to 70	
LM324PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	0 to 70	L324
LM324PWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L324
LM324PWRG3	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	L324
LM324PWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L324
LM324Y	OBSOLETE	DIESALE	Y	0		TBD	Call TI	Call TI		
M38510/11005BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510 /11005BCA

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF LM124, LM124-SP, LM124M, LM2902 :

- Catalog: [LM124](#), [LM124](#)
- Automotive: [LM2902-Q1](#)
- Enhanced Product: [LM2902-EP](#)
- Military: [LM124M](#), [LM124M](#)
- Space: [LM124-SP](#), [LM124-SP](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM124DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM224ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM224ADR	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.3	8.0	16.0	Q1
LM224ADRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM224ADRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM224DR	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.3	8.0	16.0	Q1
LM224DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM224DRG3	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.3	8.0	16.0	Q1
LM224KADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM224KDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM2902DR	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.3	8.0	16.0	Q1
LM2902DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM2902DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM2902DRG3	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.3	8.0	16.0	Q1
LM2902DRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM2902KAVQPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2902KAVQPWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2902KDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM2902KNSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
LM2902KPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2902KVQPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2902KVQPWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2902NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
LM2902PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2902PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2902PWRG3	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2902PWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM324ADBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
LM324ADR	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.3	8.0	16.0	Q1
LM324ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM324ADRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM324ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
LM324APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM324APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM324APWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM324DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM324DR	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.3	8.0	16.0	Q1
LM324DRG3	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.3	8.0	16.0	Q1
LM324DRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM324KADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM324KANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
LM324KAPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM324KDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM324KNSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
LM324KPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM324PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM324PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM324PWRG3	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM324PWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

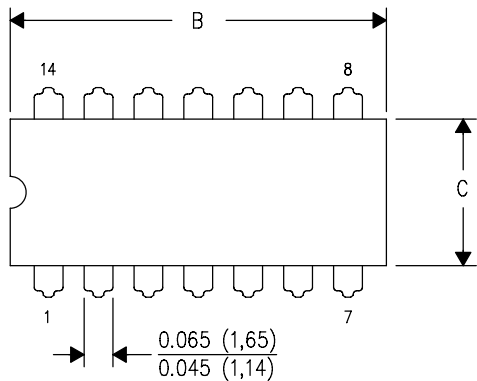
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM124DR	SOIC	D	14	2500	367.0	367.0	38.0
LM224ADR	SOIC	D	14	2500	333.2	345.9	28.6
LM224ADR	SOIC	D	14	2500	364.0	364.0	27.0
LM224ADRG4	SOIC	D	14	2500	333.2	345.9	28.6
LM224ADRG4	SOIC	D	14	2500	367.0	367.0	38.0
LM224DR	SOIC	D	14	2500	364.0	364.0	27.0
LM224DR	SOIC	D	14	2500	367.0	367.0	38.0
LM224DRG3	SOIC	D	14	2500	364.0	364.0	27.0
LM224KADR	SOIC	D	14	2500	367.0	367.0	38.0
LM224KDR	SOIC	D	14	2500	367.0	367.0	38.0
LM2902DR	SOIC	D	14	2500	364.0	364.0	27.0
LM2902DR	SOIC	D	14	2500	333.2	345.9	28.6
LM2902DR	SOIC	D	14	2500	367.0	367.0	38.0
LM2902DRG3	SOIC	D	14	2500	364.0	364.0	27.0
LM2902DRG4	SOIC	D	14	2500	333.2	345.9	28.6
LM2902KAVQPWR	TSSOP	PW	14	2000	367.0	367.0	35.0
LM2902KAVQPWRG4	TSSOP	PW	14	2000	367.0	367.0	35.0
LM2902KDR	SOIC	D	14	2500	367.0	367.0	38.0
LM2902KNSR	SO	NS	14	2000	367.0	367.0	38.0
LM2902KPWR	TSSOP	PW	14	2000	367.0	367.0	35.0

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM2902KVQPWR	TSSOP	PW	14	2000	367.0	367.0	35.0
LM2902KVQPWRG4	TSSOP	PW	14	2000	367.0	367.0	35.0
LM2902NSR	SO	NS	14	2000	367.0	367.0	38.0
LM2902PWR	TSSOP	PW	14	2000	367.0	367.0	35.0
LM2902PWR	TSSOP	PW	14	2000	364.0	364.0	27.0
LM2902PWRG3	TSSOP	PW	14	2000	364.0	364.0	27.0
LM2902PWRG4	TSSOP	PW	14	2000	367.0	367.0	35.0
LM324ADBR	SSOP	DB	14	2000	367.0	367.0	38.0
LM324ADR	SOIC	D	14	2500	364.0	364.0	27.0
LM324ADR	SOIC	D	14	2500	367.0	367.0	38.0
LM324ADRG4	SOIC	D	14	2500	367.0	367.0	38.0
LM324ANSR	SO	NS	14	2000	367.0	367.0	38.0
LM324APWR	TSSOP	PW	14	2000	364.0	364.0	27.0
LM324APWR	TSSOP	PW	14	2000	367.0	367.0	35.0
LM324APWRG4	TSSOP	PW	14	2000	367.0	367.0	35.0
LM324DR	SOIC	D	14	2500	333.2	345.9	28.6
LM324DR	SOIC	D	14	2500	364.0	364.0	27.0
LM324DRG3	SOIC	D	14	2500	364.0	364.0	27.0
LM324DRG4	SOIC	D	14	2500	333.2	345.9	28.6
LM324KADR	SOIC	D	14	2500	367.0	367.0	38.0
LM324KANSR	SO	NS	14	2000	367.0	367.0	38.0
LM324KAPWR	TSSOP	PW	14	2000	367.0	367.0	35.0
LM324KDR	SOIC	D	14	2500	367.0	367.0	38.0
LM324KNSR	SO	NS	14	2000	367.0	367.0	38.0
LM324KPWR	TSSOP	PW	14	2000	367.0	367.0	35.0
LM324PWR	TSSOP	PW	14	2000	364.0	364.0	27.0
LM324PWR	TSSOP	PW	14	2000	367.0	367.0	35.0
LM324PWRG3	TSSOP	PW	14	2000	364.0	364.0	27.0
LM324PWRG4	TSSOP	PW	14	2000	367.0	367.0	35.0

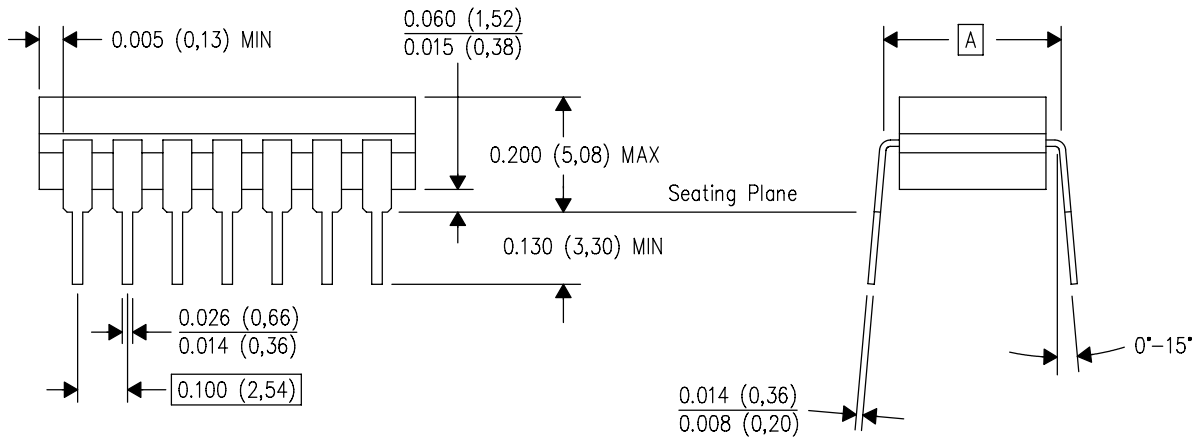
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

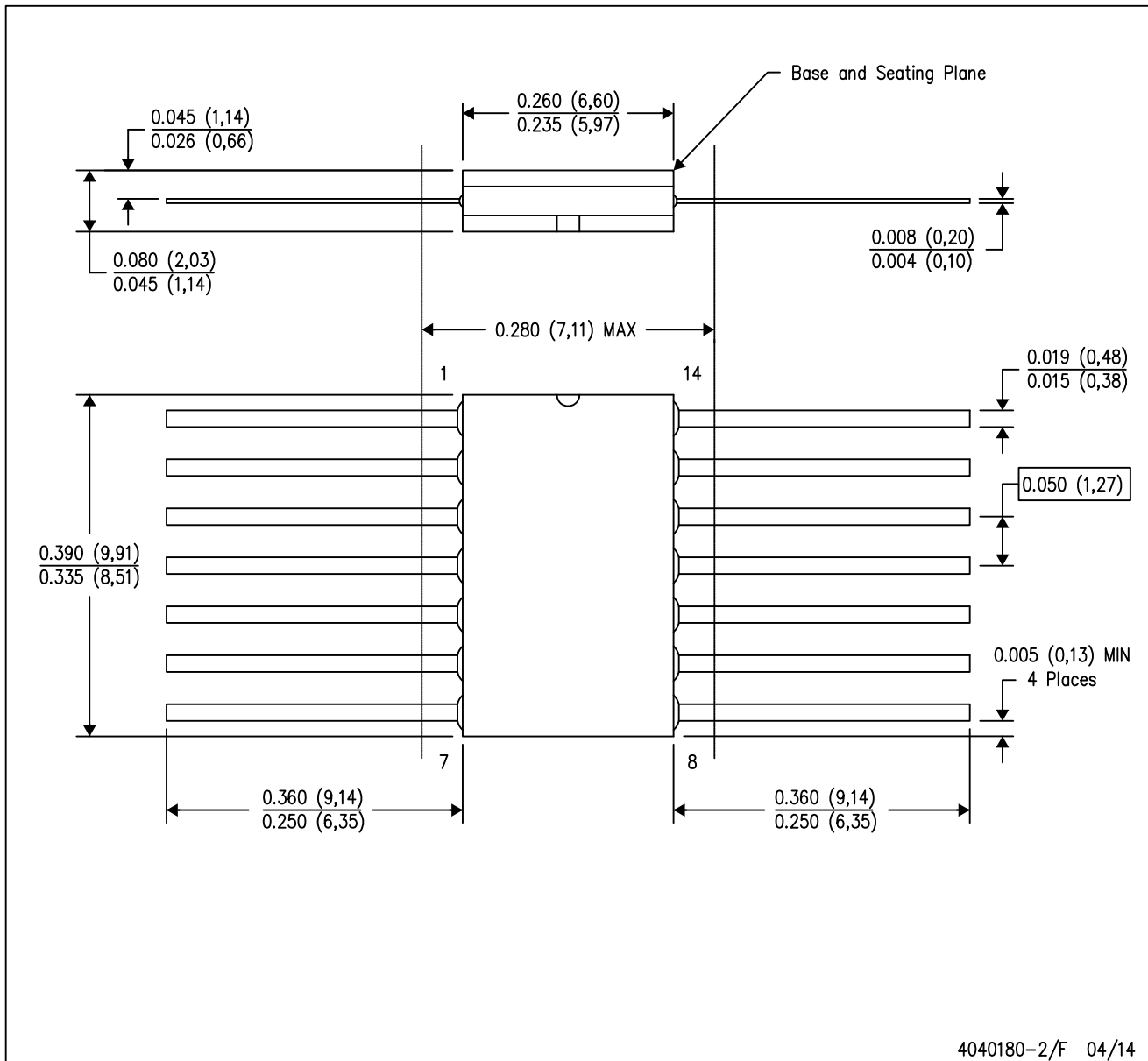


4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK

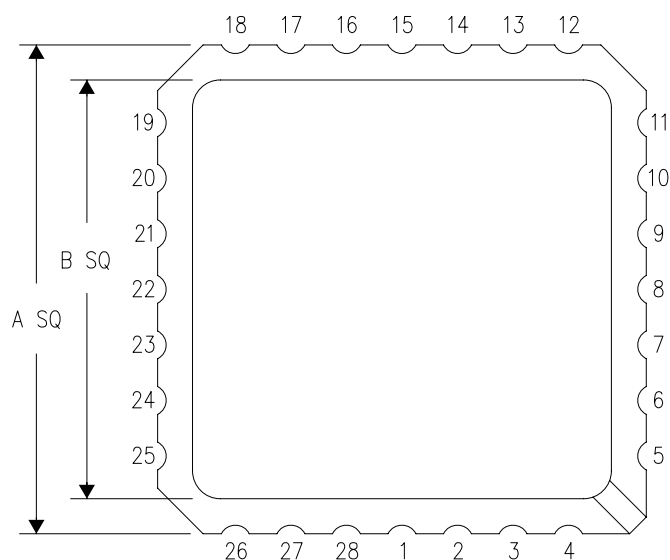


- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14

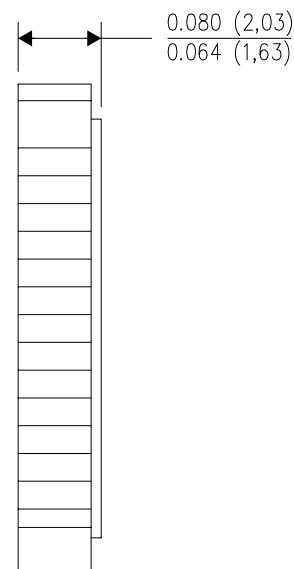
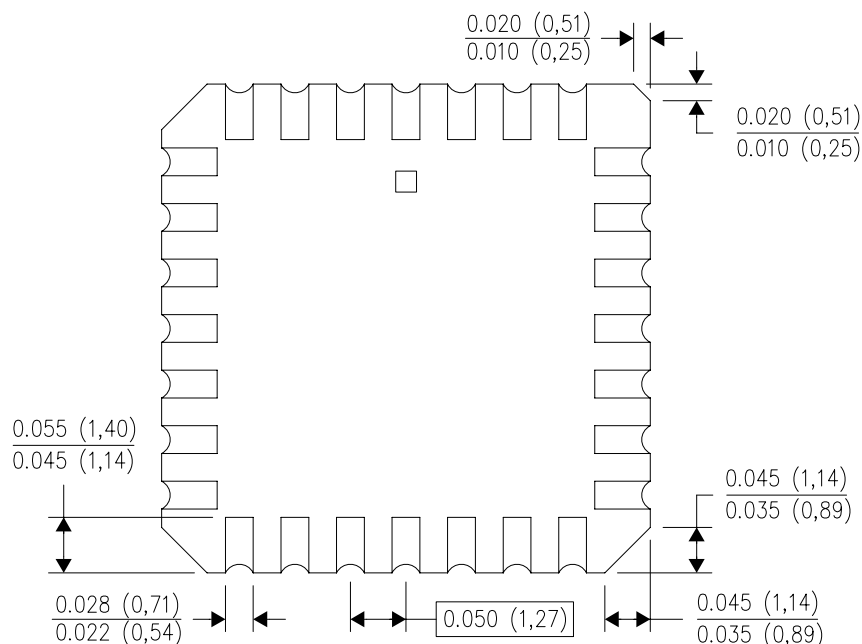
FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)

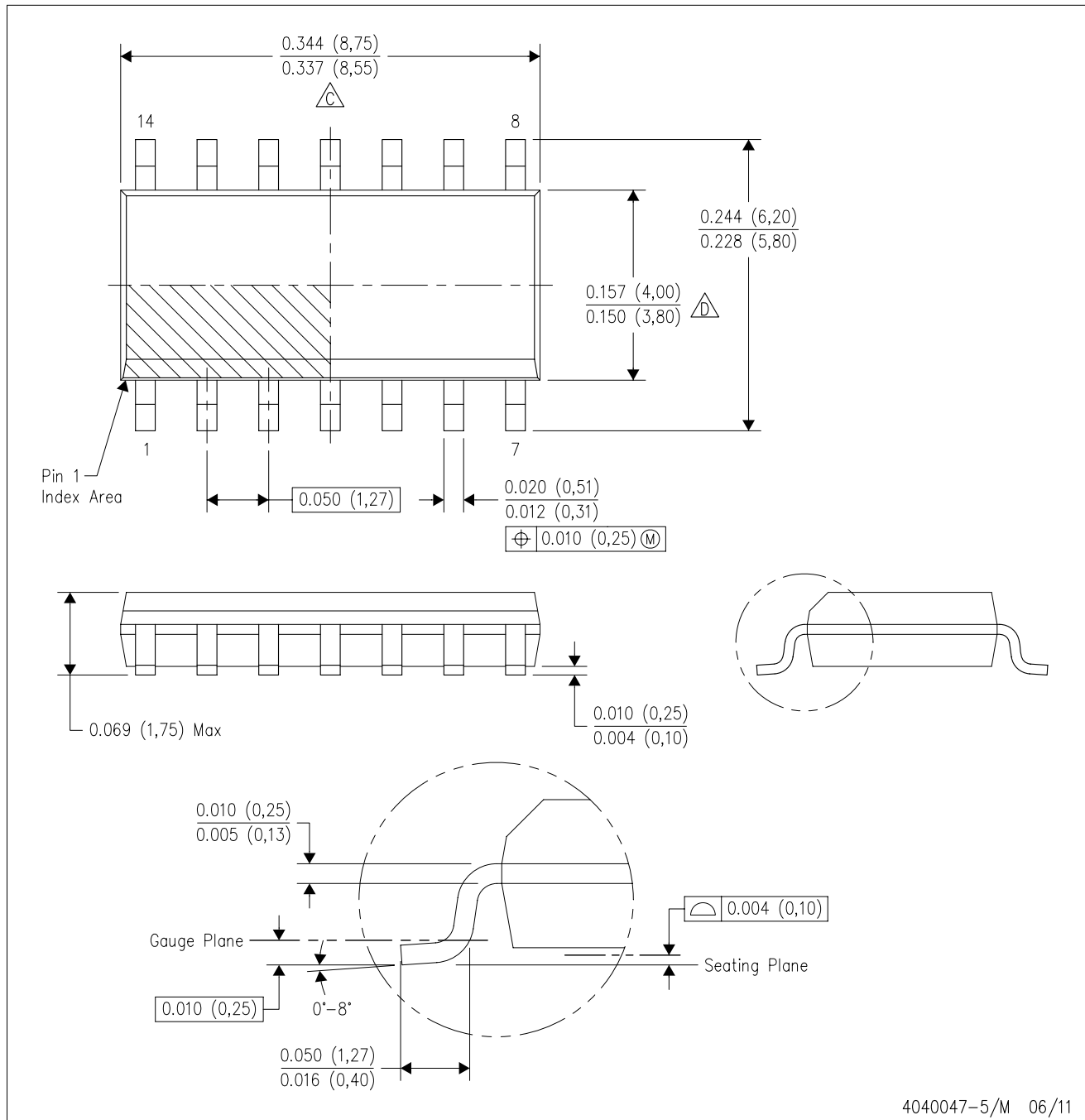




4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

D (R-PDSO-G14)

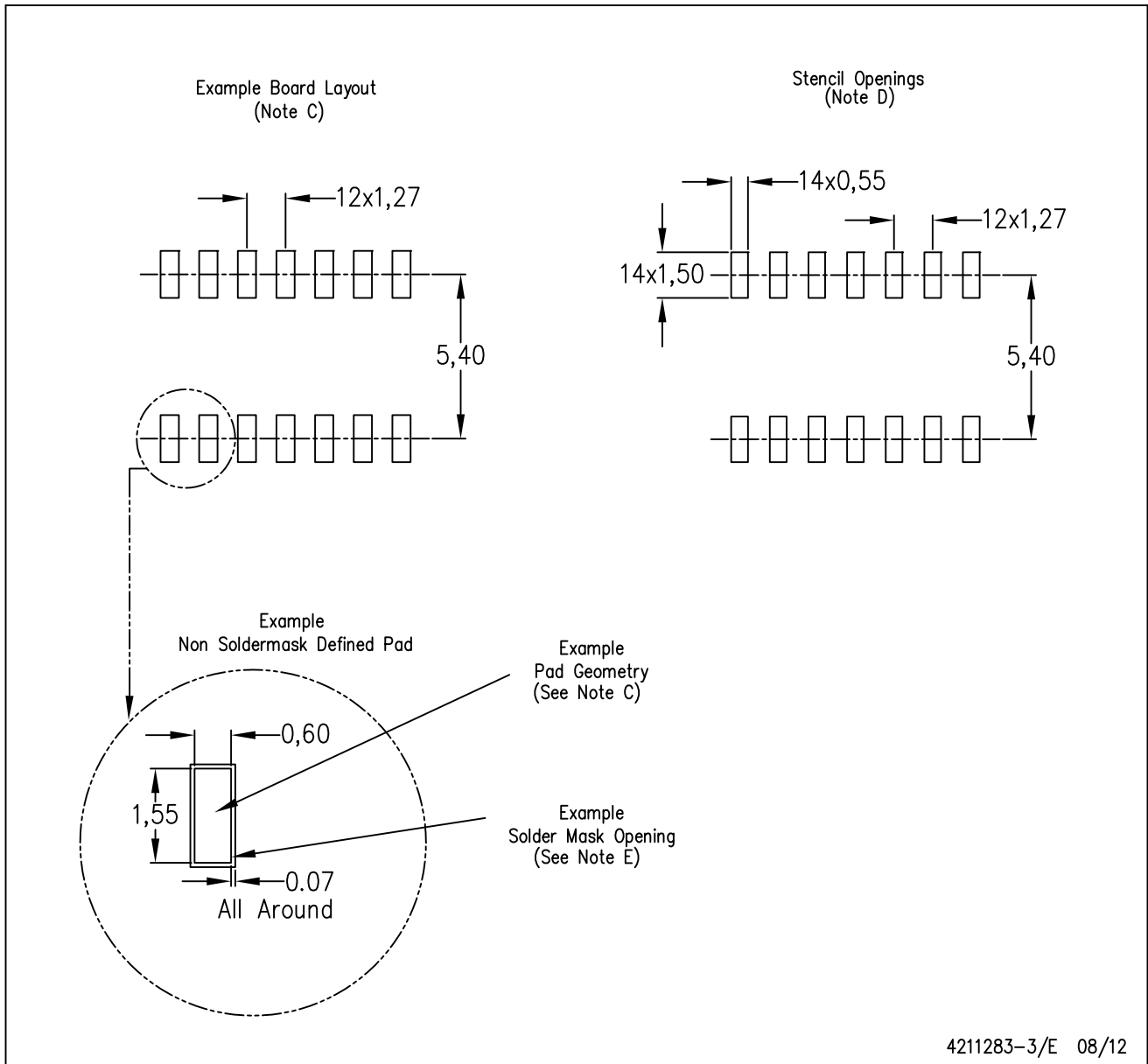
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 -  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

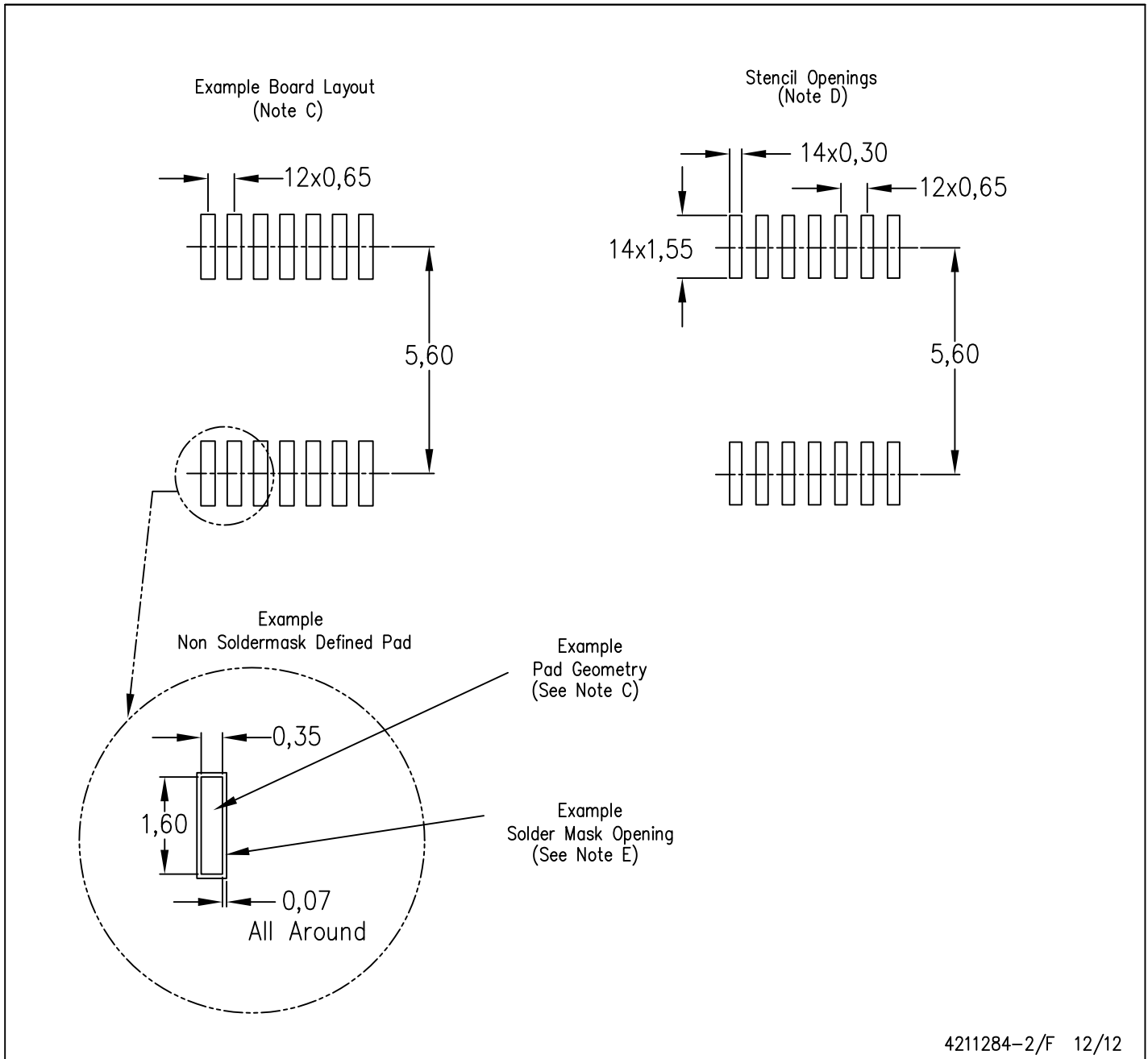
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



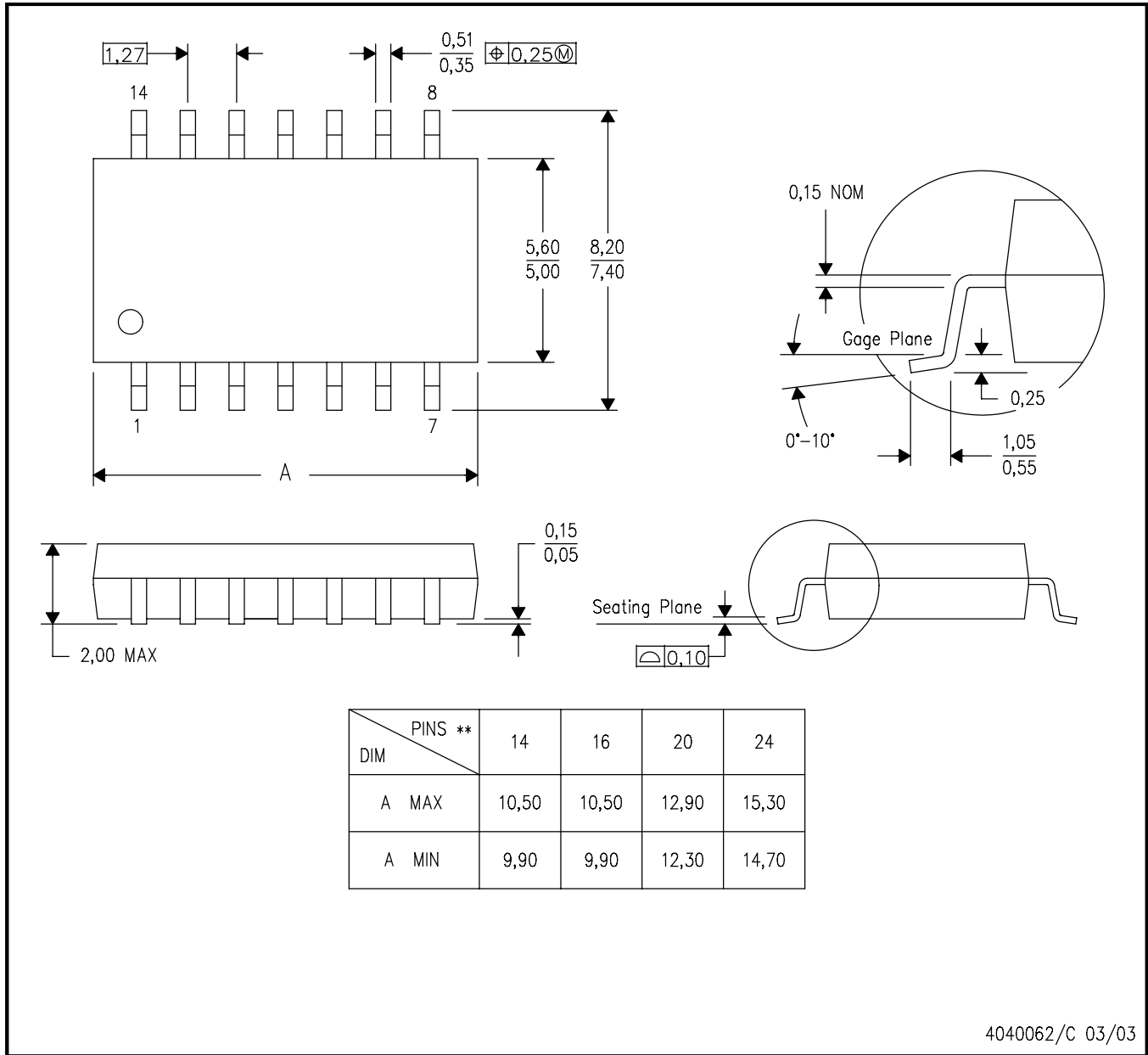
- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN

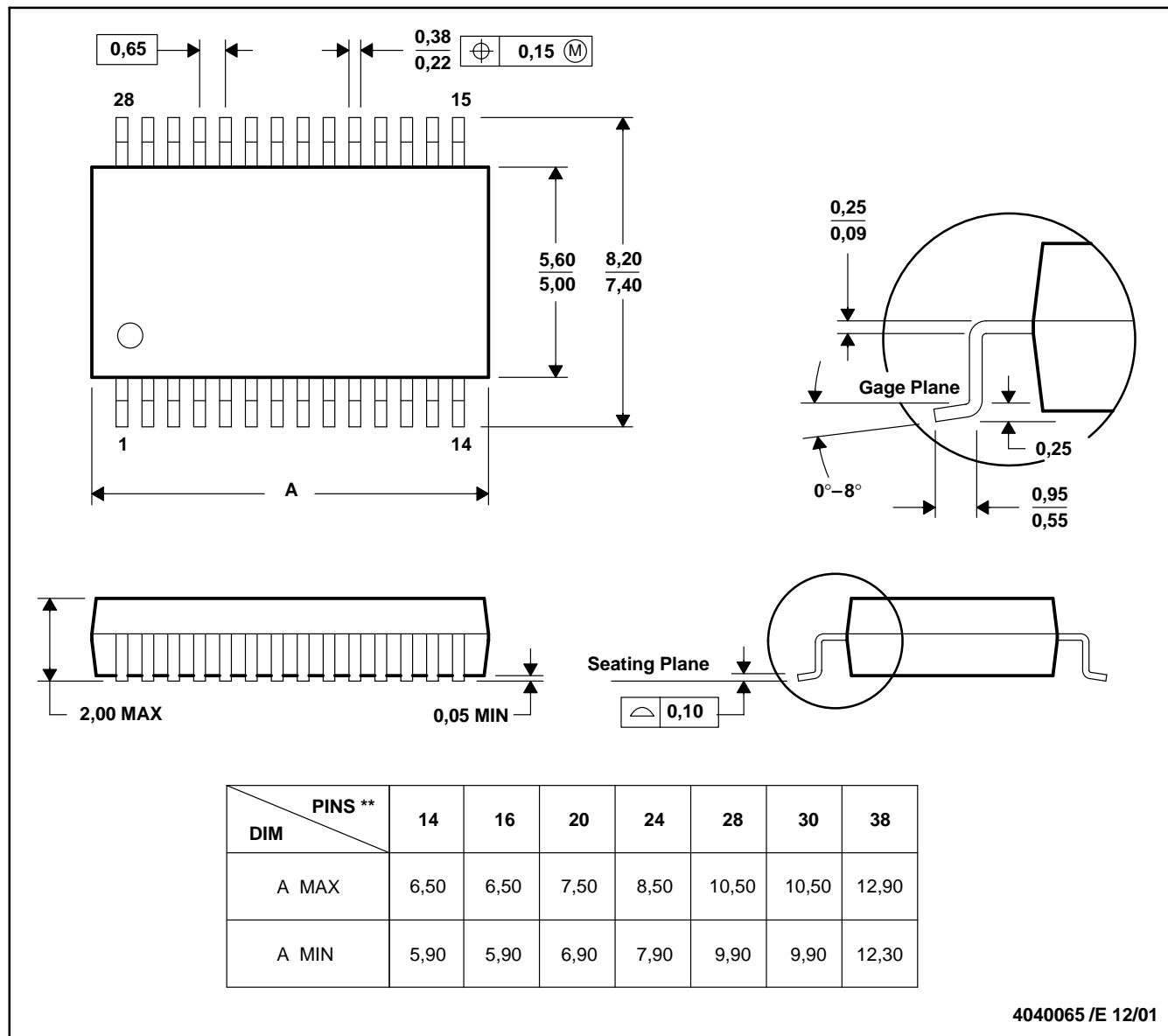


- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

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